Semiconductor Device Type: A5X SOT-89-3-MatteTin										
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	1.49	(mg) Total	Die	% of Total Weight	2.8
Silicon	7440-21-3	Die	2.80	1.49	27994		Silicon	7440-21-3	100.00	
Copper	7440-50-8	Leadframe	44.47	23.62	444670		•	Total	100.00	
Iron	7439-89-6	Leadframe	0.07	0.04	668					
Phosphorus	7723-14-0	Leadframe	0.02	0.01	178	23.67	(mg) Total	Leadframe	% of Total Weight	44.
Silver	7440-22-4	Die Attach	0.16	0.08	1574		Copper	7440-50-8	99.81	
exo-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl methacrylate	7534-94-3	Die Attach	0.01	0.01	149		Iron	7439-89-6	0.15	
Acrylic ester	Trade Secret	Die Attach	0.00	0.00	9		Phosphorus	7723-14-0	0.04	
Substituted silane	Trade Secret	Die Attach	0.00	0.00	9		•	Total	100.00	
A mixture of: 4-allyl-2,6-bis (2,3-epoxypropyl)phenol; 4- allyl-6-[3-[6-[3-(4-allyl-2,6-bis(2,3- epoxypropyl)phenoxy)-2-hydroxyp	Trade Secret	Die Attach	0.00	0.00	9					
Gold	7440-57-5	Bonding Wire	0.20	0.10	1961	0.09	(mg) Total	Die Attach	% of Total Weight	0.1
Beryllium	7440-41-7	Bonding Wire	0.00	0.00	0		Silver	7440-22-4	90.00	
Calcium	7440-70-2	Bonding Wire	0.00	0.00	0		exo-1,7,7-trimethylbicyclo[2.2.1]hept-2- yl methacrylate	7534-94-3	8.50	
Silica Fused	60676-86-0	Molding Compound	42.73	22.70	427304		Acrylic ester	Trade Secret	0.50	
Epoxy Resin	Trade Secret	Molding Compound	3.00	1.59	29962		Substituted silane	Trade Secret	0.50	
Epoxy, Cresol Novolac	29690-82-2	Molding Compound	1.26	0.67	12568		A mixture of: 4-allyl-2,6-bis (2,3- epoxypropyl)phenol; 4- allyl-6-[3-[6-[3-(4-allyl-2,6-bis(2,3- epoxypropyl)phenoxy)-2-hydroxyp	Trade Secret	0.50	
Phenol Resin	Trade Secret	Molding Compound	3.02	1.60	30163	Total 100.00				
Carbon Black	1333-86-4	Molding Compound	0.25	0.13	2514					
Bismuth	7440-69-9	Molding Compound	0.02	0.01	201	0.10	(mg) Total	Bonding Wire	% of Total Weight	0.2
Tin	7440-31-5	Lead Finish Plating	2.01	1.07	20066		Gold	7440-57-5	99.99	
Other	7439-92-1	Lead Finish Plating	0.00	0.00	2		Beryllium	7440-41-7	0.01	
		TOTA	LS: 100.00	53.12	1,000,000		Calcium	7440-70-2	0.00	
53.12 mg Total Mass							Total	100.00		
mation contained in this Material Content Declaration (MCD) consists	s of package-level information and is	not part number specific. This information is co	onsidered to be su	fficiently repr	esentative of	26.70	(mg) Total	Molding Compound	% of Total Weight	50.
umbers for the package type.							Silica Fused	60676-86-0	85.00	
							Epoxy Resin	Trade Secret	5.96	
ip Technology Incorporated designs all products to comply with global product material compliance standards, including but not limited to RoHS, REACH, and China RoHS. Additionally, Microchip s are designed to be compliant with IEC62474. For specific compliance information, please check our product material compliance website on microchip.com or ask your local sales representative.							Epoxy, Cresol Novolac Phenol Resin	29690-82-2 Trade Secret	2.50 6.00	
are designed to be compliant with IEC62474. For specific complianc	e information, please check our proc	duct material compliance website on microchip.	com or ask your ic	cai saies repi	resentativė.		Carbon Black	1333-86-4	0.50	
							Bismuth	7440-69-9	0.04	

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Tin Other

53.12